

WHAT IS CLAIMED IS:

1. A semiconductor device, comprising:

a first resin package comprising:

a semiconductor chip;

a chip electrode on a surface of said semiconductor chip;

5 a first resin sealing said semiconductor chip; and

a first package electrode on a surface of said first resin,
comprising a first electrode region connected to said chip electrode and a
second electrode region connected to said first electrode region; and

a mounted object connected to said first electrode region.

2. The semiconductor device as claimed in claim 1, further comprising:

a wiring connecting said first electrode region to said mounted object.

3. The semiconductor device as claimed in claim 2,

wherein said first electrode region is arranged along an edge of said
first resin package, and

5 wherein said second electrode region is arranged at an inner position
with respect to said first electrode region.

4. The semiconductor device as claimed in claim 3, further comprising:

a second resin sealing said first resin package and a first surface of said mounted object.

5. The semiconductor device as claimed in claim 4, further comprising:
an inner wiring connecting said chip electrode to said first electrode region.

6. The semiconductor device as claimed in claim 4, further comprising:
a conductive ball connecting said chip electrode to said first electrode region.

7. The semiconductor device as claimed in claim 1, further comprising:
a tape substrate on said first resin sealing,
wherein said first package electrode is on said tape substrate.

8. The semiconductor device as claimed in claim 7, further comprising:
a wiring connecting said first electrode region to said mounted object.

9. The semiconductor device as claimed in claim 8,
wherein said first electrode region is arranged along an edge of said first resin package, and

wherein said second electrode region is arranged at an inner position
5 with respect to said first electrode region.

10. The semiconductor device as claimed in claim 9, further comprising:

a second resin sealing said first resin package and a first surface of said mounted object.

11. The semiconductor device as claimed in claim 10, further comprising:

an inner wiring connecting said chip electrode to said first electrode region.

12. The semiconductor device as claimed in claim 10, further comprising:

a conductive ball connecting said chip electrode to said first electrode region.

13. The semiconductor device as claimed in claim 1,
wherein said mounted object is a mounting substrate.

14. The semiconductor device as claimed in claim 13,
wherein said mounted object is a second package electrode on a surface of a second resin package.

15. A semiconductor device, comprising:

a first resin package comprising:

a first semiconductor chip;

5 chip;

a first resin sealing said first semiconductor chip; and

a first package electrode on a surface of said first resin,
comprising a first electrode region connected to said first chip electrode and a
second electrode region connected to said first electrode region;

10 a second resin package comprising:

a second semiconductor chip;

a second chip electrode on a surface of said second
semiconductor chip;

a second resin sealing said second semiconductor chip; and

15 a second package electrode on a surface of said second resin,
comprising a third electrode region connected to said second chip electrode
and said first electrode region, and a fourth electrode region connected to said
third electrode region; and

a mounted object connected to said third electrode region.

16. The semiconductor device as claimed in claim 15, further
comprising:

a wiring connecting said first electrode region to said third electrode region.

17. The semiconductor device as claimed in claim 16,
wherein said third electrode region is arranged along an edge of said second region package, and

wherein said fourth electrode region is arranged at an inner position
5 with respect to said third electrode region.

18. The semiconductor device as claimed in claim 17, further comprising:

a third region sealing said first resin package and said second resin package.

19. The semiconductor device as claimed in claim 15,
wherein said mounted object is a lead frame.

20. A method of packaging a semiconductor device comprising the steps of:

connecting a chip electrode on a surface of a semiconductor chip to a package electrode, said package electrode comprising a first electrode region
5 and a second electrode region connected to said first electrode region;

sealing said semiconductor chip with a first resin to form a first resin package, such that said package electrode is exposed to a surface of said first resin package;

carrying out a burn-in test on said first resin package, using said
10 second electrode region;

connecting said first electrode region to a mounting substrate; and

sealing said first resin package and a surface of said mounting substrate to form a second resin package.

2013-03-08 10:00:00